

ABSTRACT

A method for manufacturing a plated film by bringing a film having a conductive surface into electrical contact with a cathode roll with a liquid film interposed between the film and the cathode and forming a metal plating on the conductive surface of the film, characterized in that the relation $E_0 > [(I/Cs) \times d] / \sigma$ where E_0 is the reduction potential of the metal forming the plating, I is the value of the current flowing through the cathode roll for plating, Cs is the area of the conductive surface of the film in electrical contact with the cathode roll with a liquid film interposed therebetween, d is the thickness of the gap between the cathode roll and the conductive film, and σ is the conductivity of the liquid forming the liquid film present in the gap. A cathode roll having a surface roughness R_{max} of $1 \mu m$ or less is also disclosed. Further a cathode roll having a Vickers hardness of the surface of 200 or more is disclosed.